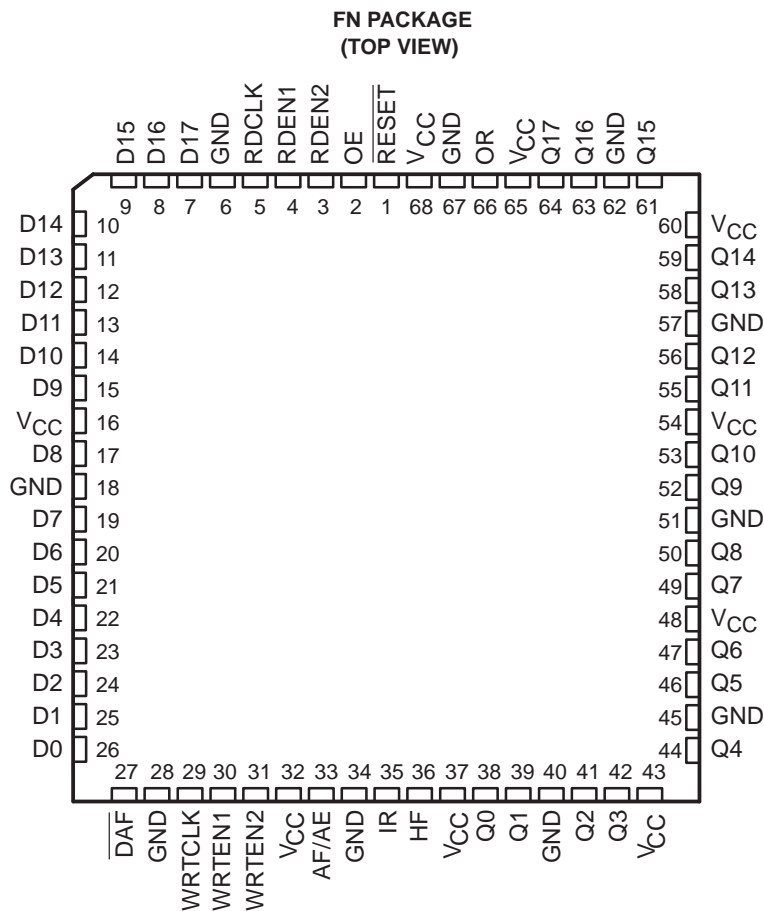


# SN74ACT7801

## 1024 × 18 CLOCKED FIRST-IN, FIRST-OUT MEMORY

SCAS111 – D3489, APRIL 1990 – REVISED MAY 1991

- Member of the Texas Instruments *Widebus™* Family
- Independent Asynchronous Inputs and Outputs
- 1024 Words × 18 Bits
- Read and Write Operations Can Be Synchronized to Independent System Clocks
- Programmable Almost-Full/Almost-Empty Flag
- Input-Ready, Output-Ready, and Half-Full Flags
- Cascadable in Word Width and/or Word Depth
- Fast Access Times of 15 ns With a 50-pF Load
- High-Output Drive for Direct Bus Interface
- 3-State Outputs
- Available in 68-Pin PLCC (FN) or Space-Saving 80-Pin Shrink Quad Flat Package (PN)



Widebus is a trademark of Texas Instruments Incorporated.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



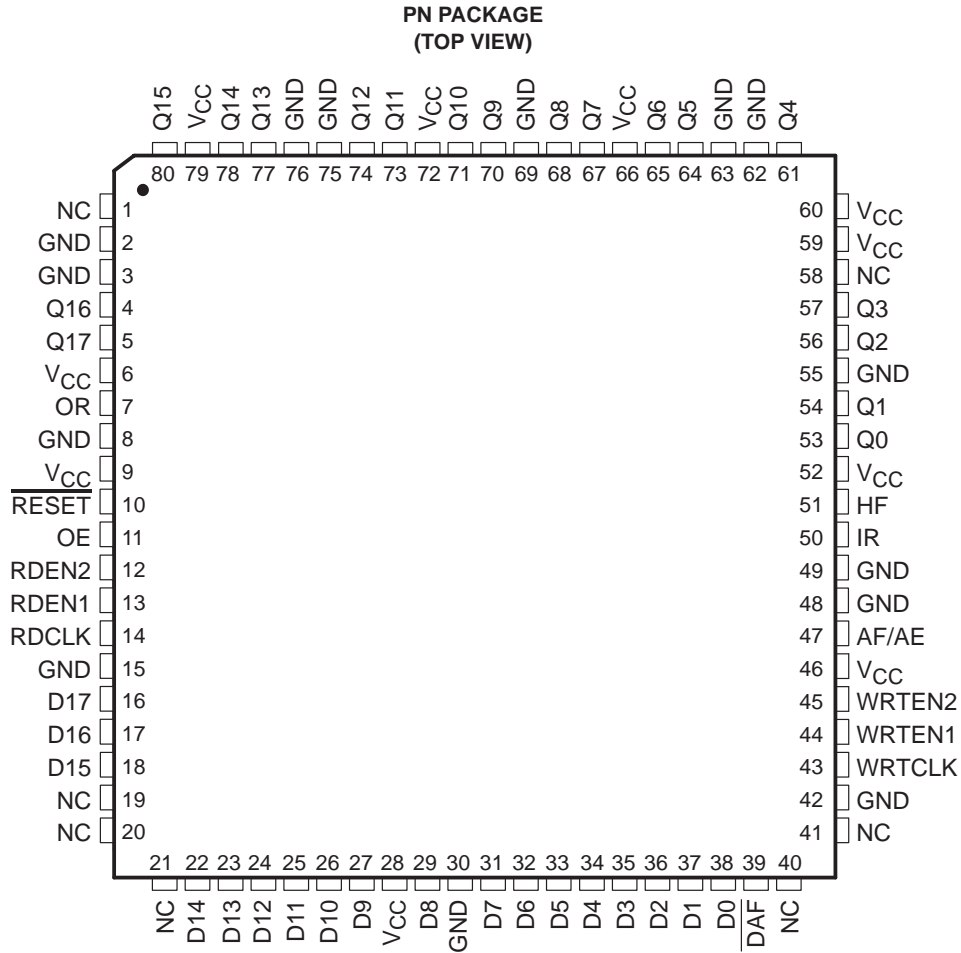
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# SN74ACT7801

## 1024 × 18 CLOCKED FIRST-IN, FIRST-OUT MEMORY

SCAS111 – D3489, APRIL 1990 – REVISED MAY 1991



NC – No internal connection

### description

A FIFO memory is a storage device that allows data to be written into and read from its array at independent data rates. The SN74ACT7801 is a 1024- × 18-bit FIFO for high speed and fast access times. It processes data at rates up to 40 MHz and access times of 15 ns in a bit-parallel format. Data outputs are noninverting with respect to the data inputs. Expansion is easily accomplished in both word width and word depth.

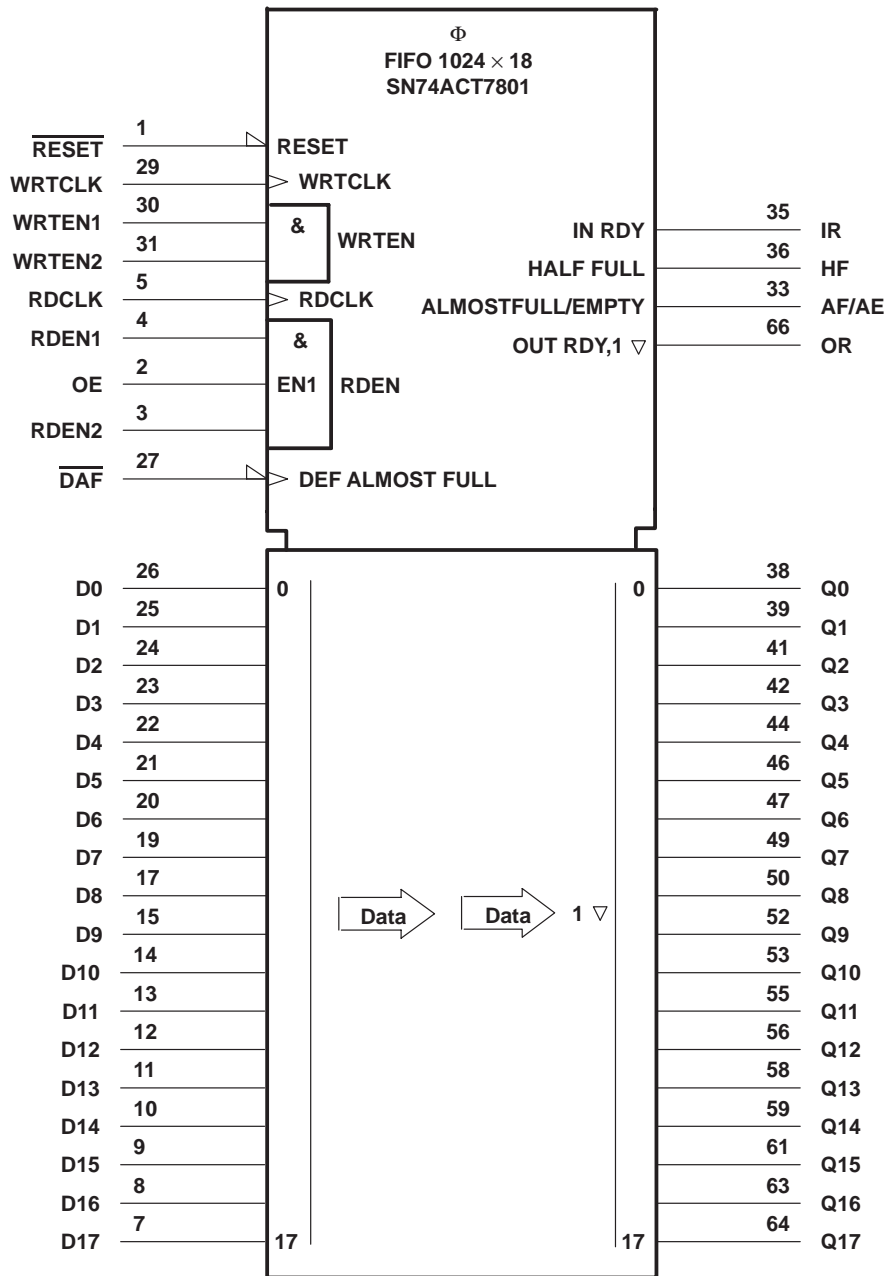
The SN74ACT7801 has normal input-bus-to-output-bus asynchronous operation. The special enable circuitry adds the ability to synchronize independent read and write (interrupts, requests) to their respective system clock.

# SN74ACT7801

## 1024 × 18 CLOCKED FIRST-IN, FIRST-OUT MEMORY

SCAS111 – D3489, APRIL 1990 – REVISED MAY 1991

logic symbol†



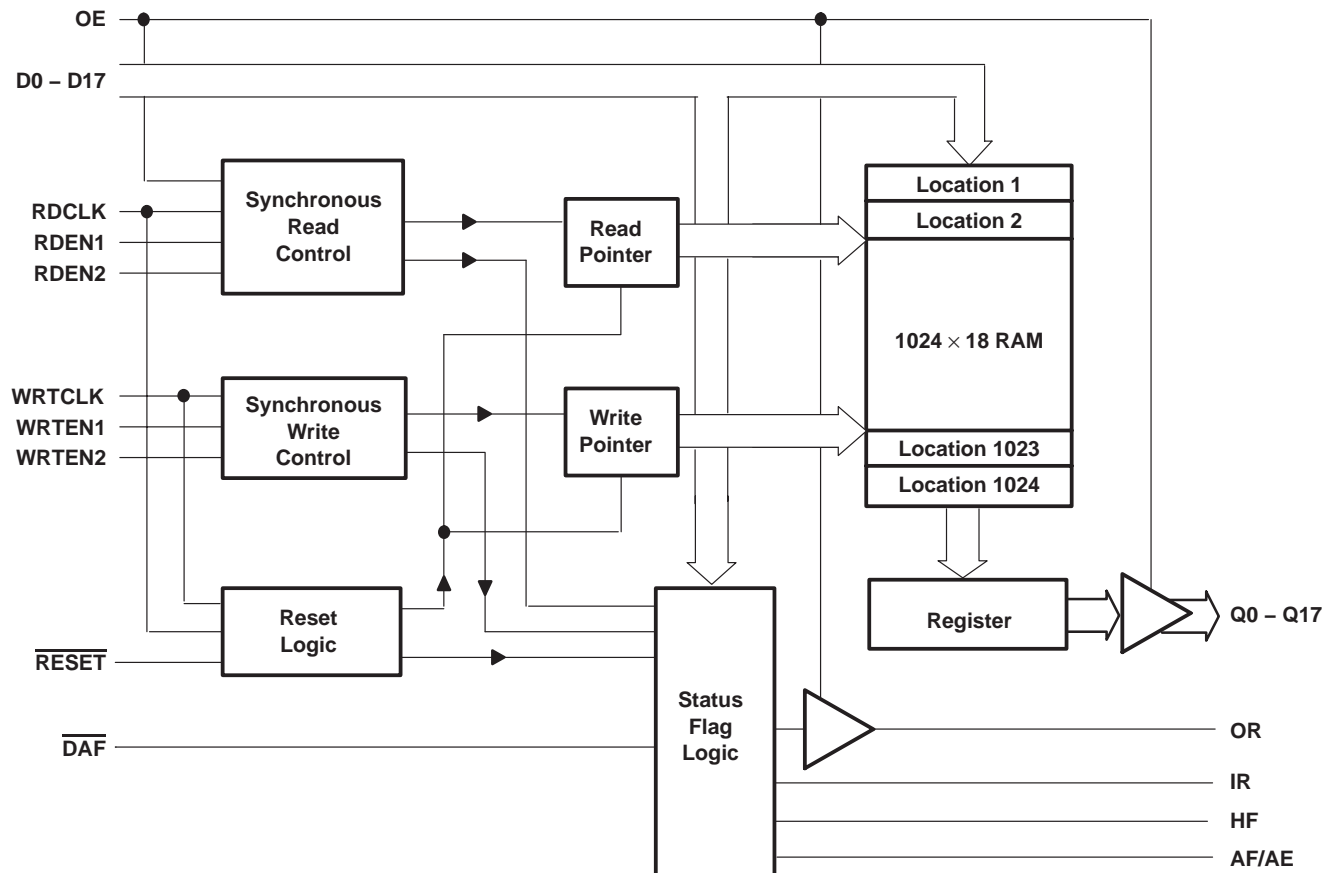
† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the FN package.

# SN74ACT7801

## 1024 × 18 CLOCKED FIRST-IN, FIRST-OUT MEMORY

SCAS111 – D3489, APRIL 1990 – REVISED MAY 1991

### functional block diagram



### functional description

#### inputs

##### data in (D0–D17)

Data inputs for 18-bit-wide data to be stored in the memory. Data lines D0–D8 also carry the almost-full/almost-empty offset value (X) on a high-to-low transition of the define almost-full ( $\overline{DAF}$ ) input.

##### reset ( $\overline{RESET}$ )

A reset is accomplished by taking reset ( $\overline{RESET}$ ) low and generating a minimum of four read-clock (RDCLK) and write-clock (WRTCLK) cycles. This ensures that the internal read and write pointers are reset and that the output-ready flag (OR), the half-full flag (HF), and the input-ready flag (IR) are low; the almost-full/almost-empty flag (AF/AE) is high. The FIFO must be reset upon power up. With the define almost-full ( $\overline{DAF}$ ) input at a low level, a low pulse on  $\overline{RESET}$  defines the AF/AE status flag using the almost-full/almost-empty offset value (X), where X is the value previously stored. With  $\overline{DAF}$  at a high level, a low-level pulse on  $\overline{RESET}$  defines the AF/AE flag using the default value of X = 256.

##### write enables (WRTEN1, WRTEN2)

The write enables (WRTEN1, WRTEN2) must be high before the rising edge of write clock (WRTCLK) for a word to be written into memory. The write enables do not affect the storage of the almost-full/almost-empty offset value (X).

---

## functional description (continued)

### write clock (WRTCLK)

Data is written into memory on a low-to-high transition of the write clock (WRTCLK) if the input-ready flag output (IR) and the write-enable control inputs (WRTEN1, WRTEN2) are high. WRTCLK is a free-running clock and functions as the synchronizing clock for all data transfers into the FIFO. The IR flag output is also driven synchronously with respect to the WRTCLK signal.

### read enables (RDEN1, RDEN2)

Both read enables (RDEN1, RDEN2) must be high before the rising edge of read clock (RDCLK) to read a word out of memory. The read enables are not used to read the first word stored in memory.

### read clock (RDCLK)

Data is read out of memory on a low-to-high transition at the read-clock (RDCLK) input if the output-ready flag output (OR) and the output-enable (OE) and read-enable (RDEN1, RDEN2) control inputs are high. RDCLK is a free-running clock and functions as the synchronizing clock for all data transfers out of the FIFO. The OR flag is also driven synchronously with respect to the RDCLK signal.

### define almost-full ( $\overline{DAF}$ )

The high-to-low transition of the define almost-full ( $\overline{DAF}$ ) input stores the binary value of data inputs D0–D8 as the almost-full/almost-empty offset value (X). With  $\overline{DAF}$  held low, a low pulse on the reset ( $\overline{RESET}$ ) input defines the almost-full/almost-empty flag (AF/AE) using X.

### output enable (OE)

The data-out (Q0–Q17) outputs and the output-ready flag (OR) are in the high-impedance state when the output enable (OE) input is low. OE must be high before the rising edge of read clock (RDCLK) to read a word from memory.

## outputs

### data out (Q0–Q17)

The first data word to be loaded into the FIFO is moved to the data out (Q0–Q17) register on the rising edge of the third read clock (RDCLK) pulse to occur after the first valid write. The read-enable (RDEN1, RDEN2) inputs do not affect this operation. Following data is unloaded on the rising edge of RDCLK when RDEN1, RDEN2, and the output-ready flag (OR) are high.

### input-ready flag (IR)

The input-ready flag (IR) is high when the FIFO is not full and low when the device is full. During reset, the IR flag is driven low on the rising edge of the second write clock (WRTCLK) pulse. The IR flag is driven high on the rising edge of the second WRTCLK pulse after  $\overline{RESET}$  goes high. After the FIFO is filled and IR is driven low, IR is driven high on the second WRTCLK pulse after the first valid read.

### output-ready flag (OR)

The output-ready flag (OR) is high when the FIFO is not empty and low when it is empty. During reset, the OR flag is set low on the rising edge of the third read clock (RDCLK) pulse. The OR flag is set high on the rising edge of the third RDCLK pulse to occur after the first word is written into the FIFO. OR is set low on the rising edge of the first RDCLK pulse after the last word is read.

### half-full status flag (HF)

The half-full flag (HF) is high when the FIFO contains 513 or more words and is low when it contains 512 or less words.

# SN74ACT7801

## 1024 × 18 CLOCKED FIRST-IN, FIRST-OUT MEMORY

SCAS111 – D3489, APRIL 1990 – REVISED MAY 1991

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### functional description (continued)

#### almost-full/almost-empty status flag (AF/AE)

The almost-full/almost-empty flag (AF/AE) is defined by the almost-full/almost-empty offset value (X). The AF/AE flag is high when the FIFO contains (X + 1) or less words or (1025 – X) or more words. The AF/AE flag is low when the FIFO contains between (X + 2) and (1024 – X) words.

#### programming procedure for AF/AE

The almost-full/almost-empty flag (AF/AE) is programmed during each reset cycle. The almost-full/almost-empty offset value (X) is either a user-defined value or the default value of X = 256. Below are instructions to program AF/AE using both methods.

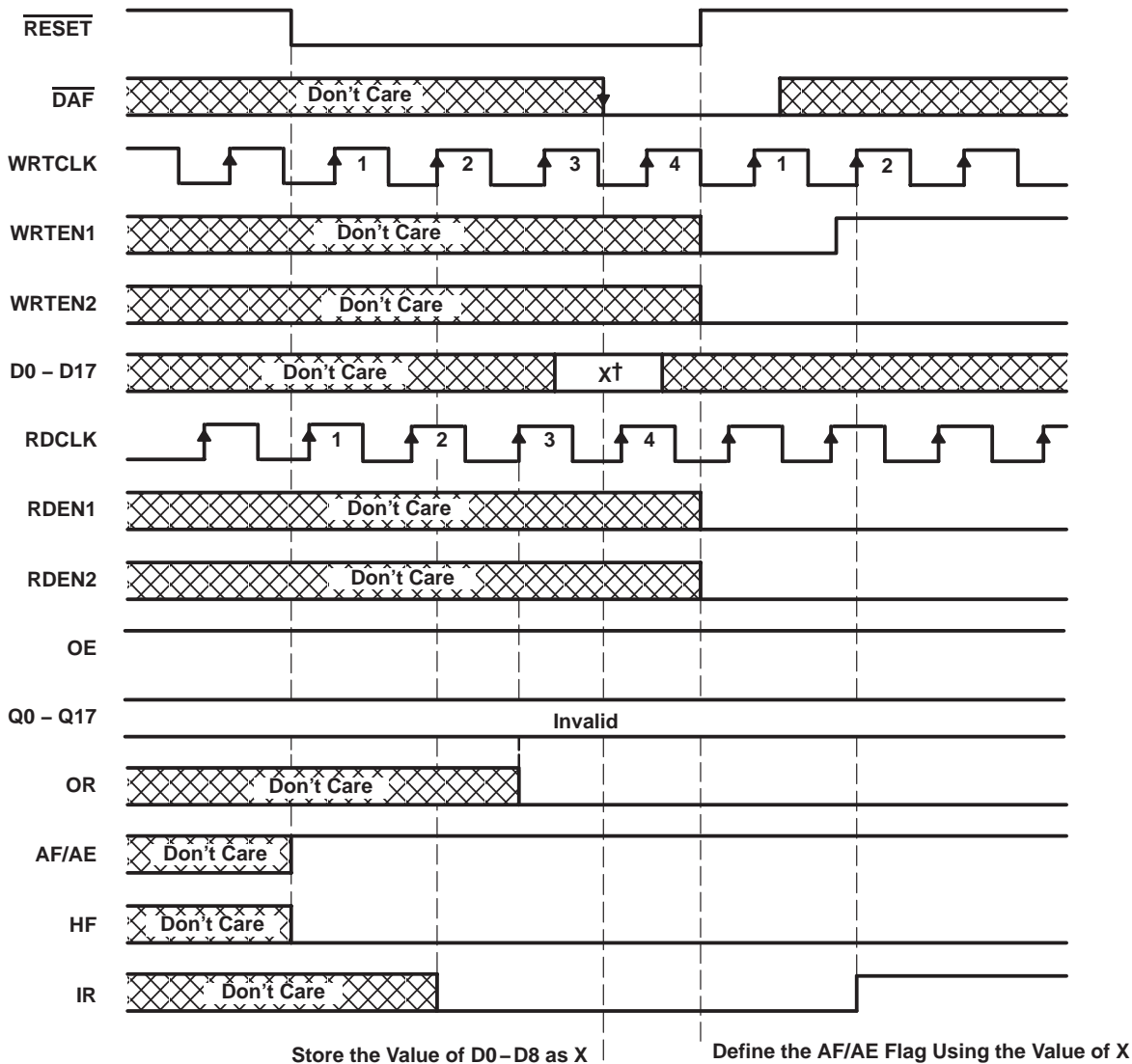
##### *user-defined X:*

1. Take  $\overline{\text{DAF}}$  from high to low.
2. If  $\overline{\text{RESET}}$  is not already low, take  $\overline{\text{RESET}}$  low.
3. With  $\overline{\text{DAF}}$  held low, take  $\overline{\text{RESET}}$  high. This defines the AF/AE flag using X.
4. To retain the current offset for the next reset, keep  $\overline{\text{DAF}}$  low.

##### *default X:*

To redefine the AF/AE flag using the default value of X = 256, hold  $\overline{\text{DAF}}$  high during the reset cycle.

timing diagrams



† X is the binary value of D0-D8 only.

**Figure 1. Reset Cycle: Define AF/AE Using the Value of X**

# SN74ACT7801 1024 × 18 CLOCKED FIRST-IN, FIRST-OUT MEMORY

SCAS111 – D3489, APRIL 1990 – REVISED MAY 1991

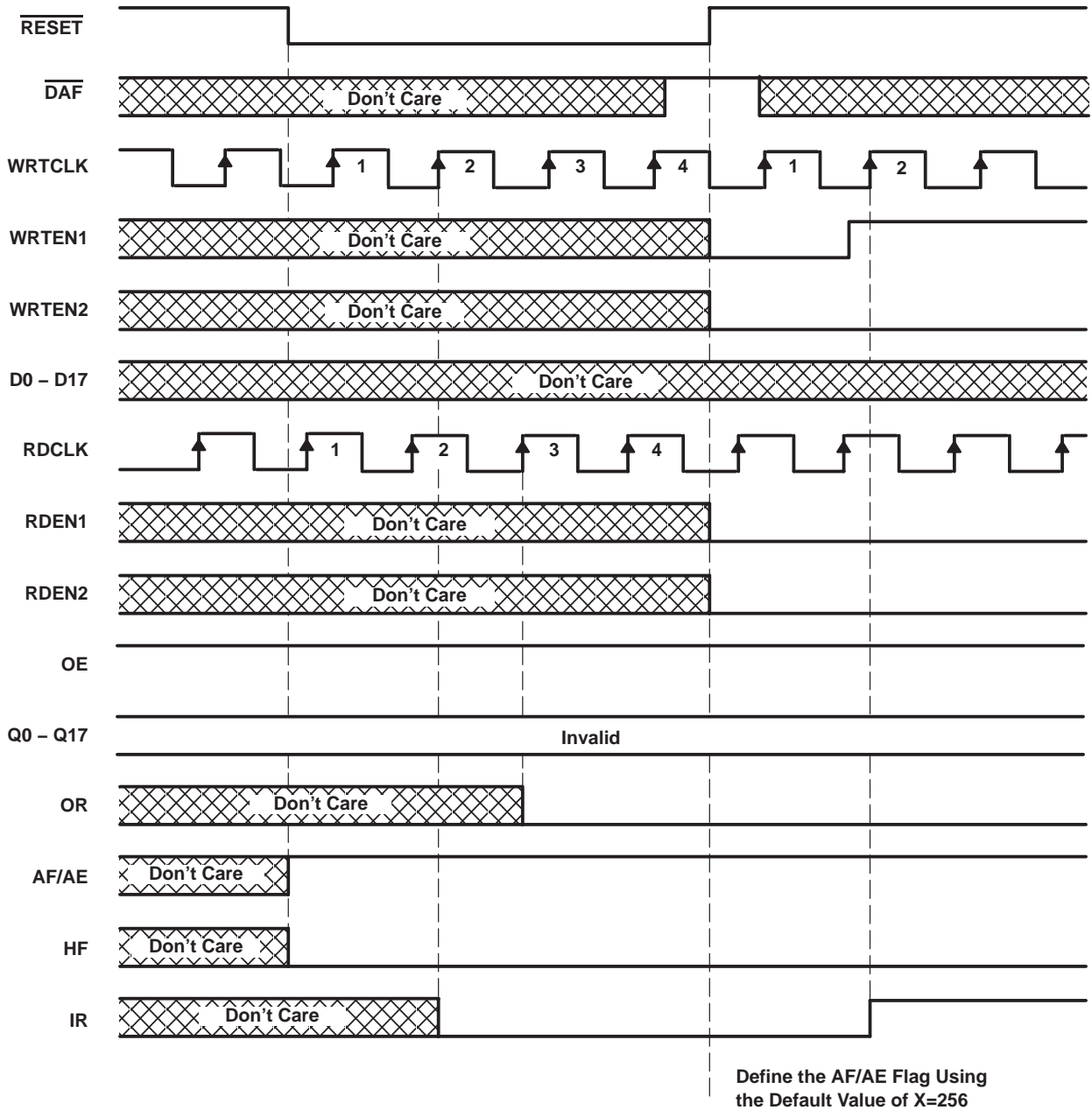


Figure 2. Reset Cycle: Define AF/AE Using the Default Value



# SN74ACT7801

## 1024 × 18 CLOCKED FIRST-IN, FIRST-OUT MEMORY

SCAS111 – D3489, APRIL 1990 – REVISED MAY 1991

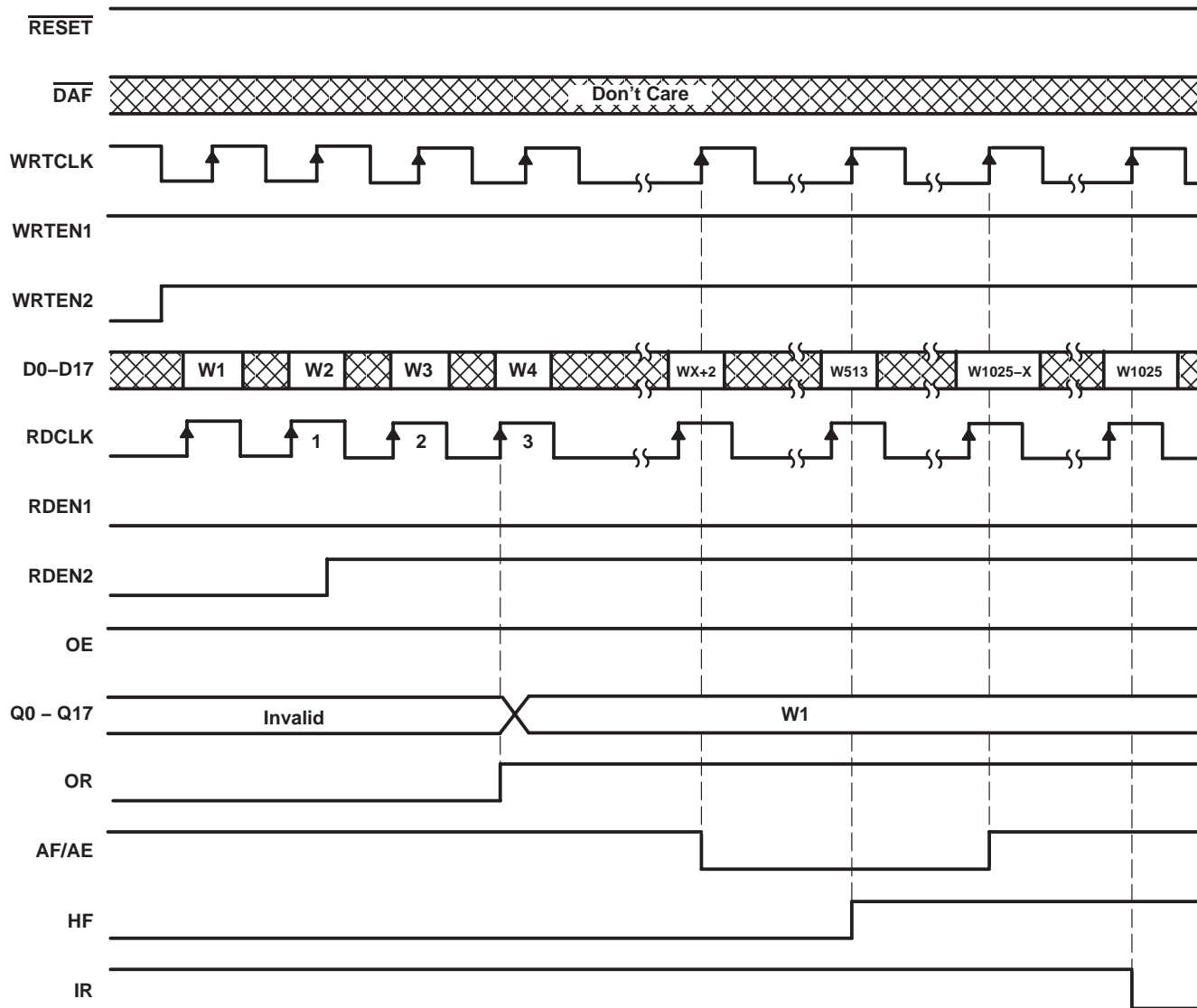


Figure 3. Write

# SN74ACT7801

## 1024 × 18 CLOCKED FIRST-IN, FIRST-OUT MEMORY

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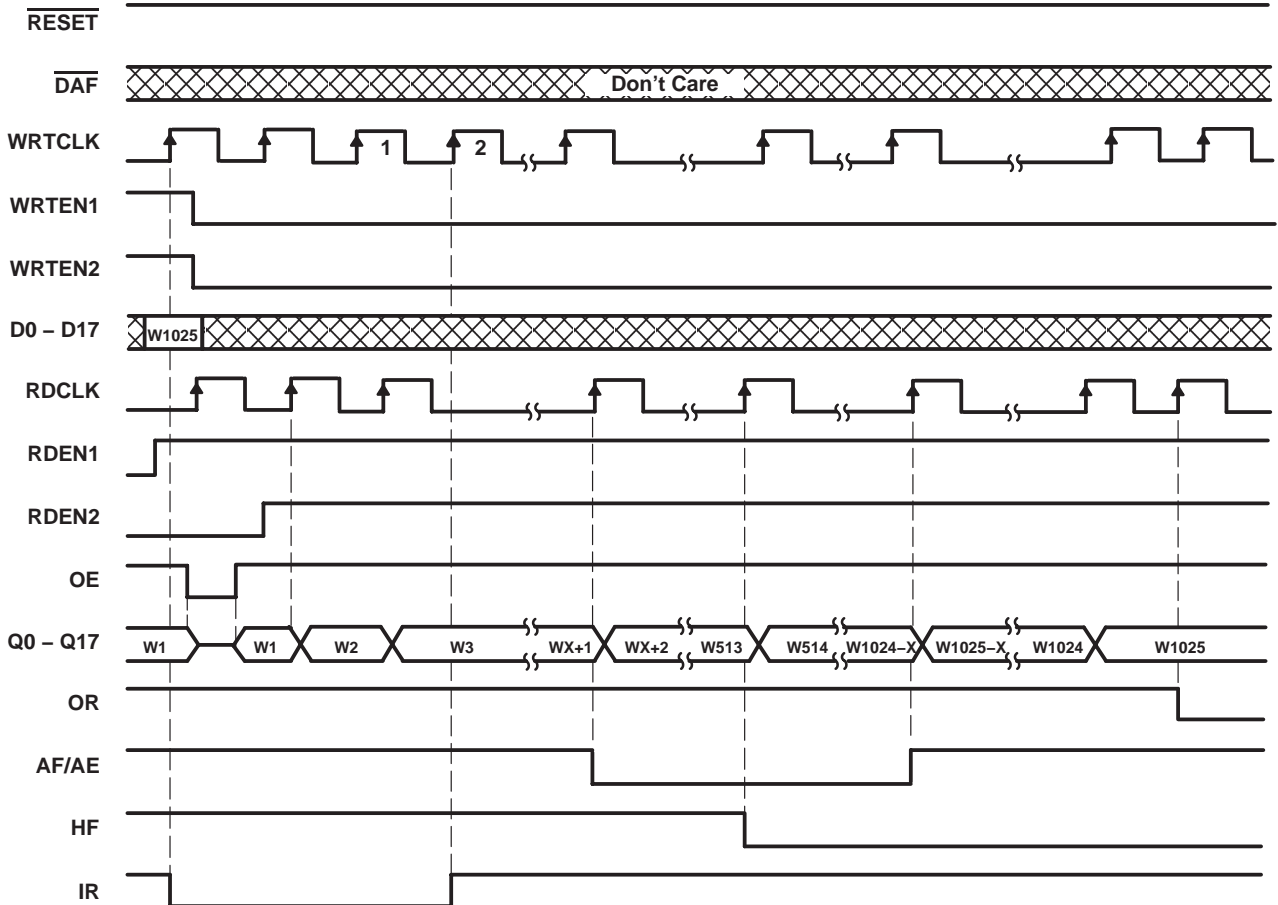


Figure 4. Read

# SN74ACT7801

## 1024 × 18 CLOCKED FIRST-IN, FIRST-OUT MEMORY

SCAS111 – D3489, APRIL 1990 – REVISED MAY 1991

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$ .....	–0.5 V to 7 V
Input voltage, $V_I$ .....	7 V
Voltage applied to a disabled 3-state output .....	5.5 V
Operating free-air temperature range .....	0°C to 70°C
Storage temperature range .....	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### recommended operating conditions

		'ACT7801-15		'ACT7801-18		'ACT7801-20		UNIT	
		MIN	MAX	MIN	MAX	MIN	MAX		
$V_{CC}$	Supply voltage	4.5	5.5	4.5	5.5	4.5	5.5	V	
$V_{IH}$	High-level input voltage	2		2		2		V	
$V_{IL}$	Low-level input voltage		0.8		0.8		0.8	V	
$I_{OH}$	High-level output current		–8		–8		–8	mA	
$I_{OL}$	Low-level output current		16		16		16	mA	
$f_{clock}$	Clock frequency	40		35		28.5		MHz	
$t_w$	Pulse duration	Data in (D0–D17) high or low	10		12		14		ns
		WRTCLK high	7		8.5		10		
		WRTCLK low	15		15		15		
		RDCLK high	7		8.5		10		
		RDCLK low	15		15		15		
		$\overline{DAF}$ high	10		10		10		
		WRTEN1, WRTEN2 high or low	10		10		10		
		OE, RDEN1, RDEN2 high or low	10		10		10		
$t_{su}$	Setup time	Data in (D0–D17) before WRTCLK↑	5		5		5		ns
		WRTEN1, WRTEN2 before WRTCLK↑	5		5		5		
		OE, RDEN1, RDEN2 before RDCLK↑	5		5		5		
		Reset: $\overline{RESET}$ low before first WRTCLK and RDCLK↑	7		7		7		
		Define AF/AE: D0–D8 before $\overline{DAF}$ ↓	5		5		5		
		Define AF/AE: $\overline{DAF}$ ↓ before $\overline{RESET}$ ↑	7		7		7		
		Define AF/AE (default): $\overline{DAF}$ high before $\overline{RESET}$ ↑	5		5		5		
$t_h$	Hold time	Data in (D0–D17) after WRTCLK↑	1		1		1		ns
		WRTEN1, WRTEN2 after WRTCLK↑	1		1		1		
		OE, RDEN1, RDEN2 after RDCLK↑	1		1		1		
		Reset: $\overline{RESET}$ low after fourth WRTCLK and RDCLK↑	0		0		0		
		Define AF/AE: D0–D8 after $\overline{DAF}$ ↓	1		1		1		
		Define AF/AE: $\overline{DAF}$ low after $\overline{RESET}$ ↑	0		0		0		
		Define AF/AE (default): $\overline{DAF}$ high after $\overline{RESET}$ ↑	1		1		1		
$T_A$	Operating free-air temperature	0	70	0	70	0	70	°C	



# SN74ACT7801

## 1024 × 18 CLOCKED FIRST-IN, FIRST-OUT MEMORY

SCAS111 – D3489, APRIL 1990 – REVISED MAY 1991

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V <sub>OH</sub>		V <sub>CC</sub> = 4.5 V, I <sub>OH</sub> = -8 mA	2.4			V
V <sub>OL</sub>		V <sub>CC</sub> = 4.5 V, I <sub>OL</sub> = 16 mA			0.5	V
I <sub>I</sub>		V <sub>CC</sub> = 5.5 V, V <sub>I</sub> = V <sub>CC</sub> or 0			±5	μA
I <sub>OZ</sub>		V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = V <sub>CC</sub> or 0			±5	μA
I <sub>CC1</sub> ‡	Supply current	f <sub>clock</sub> = 25 MHz§		200	230	mA
I <sub>CC2</sub> ‡	Standby current	V <sub>IH</sub> = WRTCLK, V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>		20	25	mA
I <sub>CC3</sub> ‡	Power-down current	V <sub>I</sub> = V <sub>CC</sub> - 0.2 V or 0			400	μA
C <sub>i</sub>		V <sub>I</sub> = 0, f = 1 MHz		4		pF
C <sub>o</sub>		V <sub>O</sub> = 0, f = 1 MHz		8		pF

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C<sub>L</sub> = 50 pF (see Figures 9 and 10)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	'ACT7801-15			'ACT7801-18		'ACT7801-20		UNIT
			MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
f <sub>max</sub>	WRTCLK or RDCLK		40			35		28.5		MHz
t <sub>pd</sub>	RDCLK↑	Any Q	5	12	15	5	18	5	20	ns
t <sub>pd</sub> ¶			10.5							
t <sub>pd</sub>	WRTCLK↑	IR	4		10	4	12	4	14	ns
t <sub>pd</sub>	RDCLK↑	OR	4		10	4	12	4	14	ns
t <sub>pd</sub>	WRTCLK↑	AF/AE	7		20	7	22	7	24	ns
	RDCLK↑		7		20	7	22	7	24	
t <sub>PLH</sub>	WRTCLK↑	HF	6		19	6	21	6	23	ns
t <sub>PHL</sub>	RDCLK↑		6		19	6	21	6	23	
t <sub>PLH</sub>	RESET↓	AF/AE	4		19	4	21	4	23	ns
t <sub>PHL</sub>		HF	4		21	4	23	4	25	
t <sub>en</sub>	OE	Any Q, OR	4		11	4	11	4	11	ns
t <sub>dis</sub>			2		14	2	14	2	14	

† All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

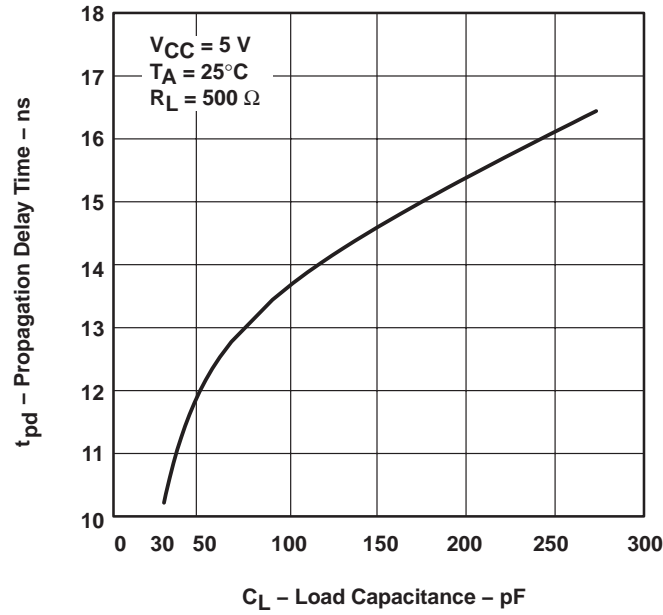
‡ I<sub>CC</sub> tested with outputs open.

§ For frequencies greater than 25 MHz, I<sub>CC</sub> = 230 mA + (6 mA × [f - 25 MHz]).

¶ This parameter is measured with C<sub>L</sub> = 30 pF (see Figure 5).

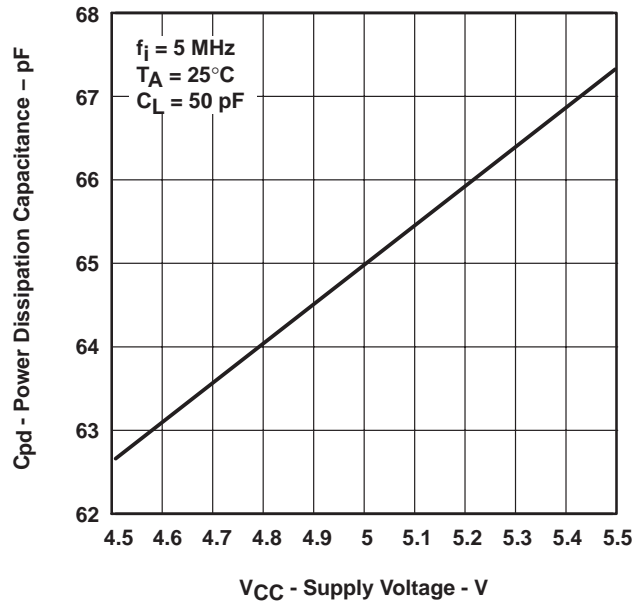
**TYPICAL CHARACTERISTICS**

**PROPAGATION DELAY TIME  
vs  
LOAD CAPACITANCE**



**Figure 5**

**POWER DISSIPATION CAPACITANCE  
vs  
SUPPLY VOLTAGE**



**Figure 6**

# SN74ACT7801

## 1024 × 18 CLOCKED FIRST-IN, FIRST-OUT MEMORY

SCAS111 – D3489, APRIL 1990 – REVISED MAY 1991

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### calculating power dissipation

With  $I_{CCF}$  taken from Figure 6, the maximum power dissipation based on all data outputs changing states on each read may be calculated using:

$$P_t = V_{CC} \times [I_{CCF} + (N \times \Delta I_{CC} \times dc)] + \Sigma(C_L \times V_{CC}^2 \times fo)$$

A more accurate power calculation based on device use and average number of data outputs switching can be found using:

$$P_t = V_{CC} \times [I_{CC} + (N \times \Delta I_{CC} \times dc)] + \Sigma(C_{pd} \times V_{CC}^2 \times fi) + \Sigma(C_L \times V_{CC}^2 \times fo)$$

where:

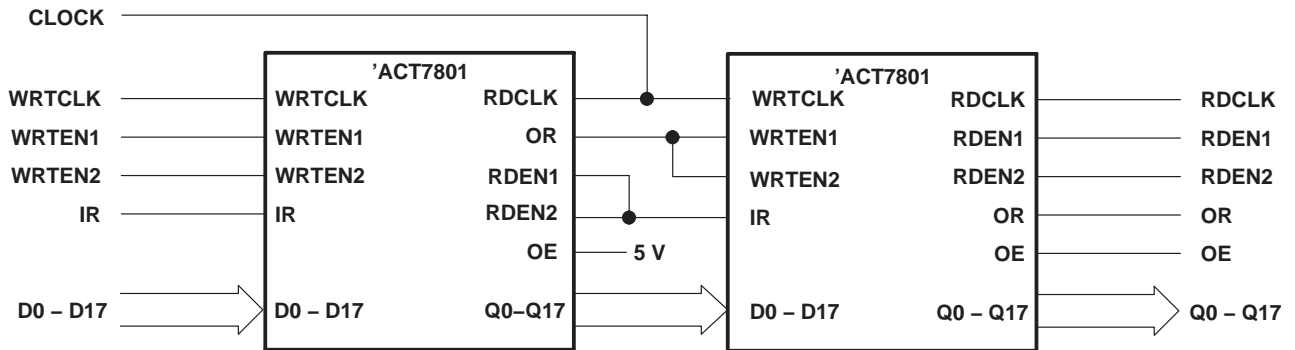
- $I_{CC}$  = power-down  $I_{CC}$  maximum
- $N$  = number of inputs driven by a TTL device
- $\Delta I_{CC}$  = increase in supply current
- $dc$  = duty cycle of inputs at a TTL high level of 3.4 V
- $C_{pd}$  = power dissipation capacitance
- $C_L$  = output capacitive load
- $f_i$  = data input frequency
- $f_o$  = data output frequency

**APPLICATION INFORMATION**

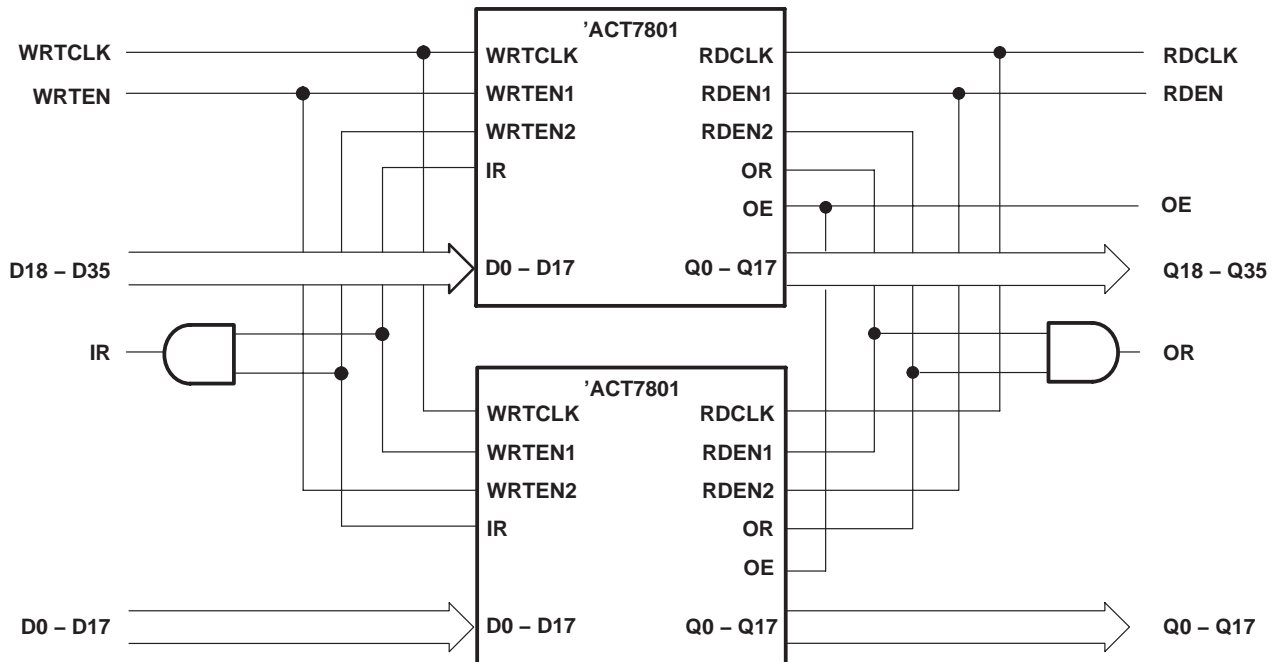
**expanding the SN74ACT7801**

The SN74ACT7801 is expandable in width and depth. Expanding in word depth offers special timing considerations:

1. After the first data word is loaded into the FIFO, the word is unloaded, and the output-ready flag output (OR) goes high after  $(N \times 3)$  read clock (RDCLK) cycles, where N is the number of devices used in depth expansion.
2. After the FIFO is filled, the input-ready flag output (IR) goes low, the first word is unloaded, and the IR flag output is driven high after  $(N \times 2)$  write clock cycles, where N is the number of devices used in depth expansion.



**Figure 7. Word-Depth Expansion: 2048 Words × 18 Bits, N = 2**



**Figure 8. Word-Width Expansion: 1024 Words × 36 Bits**

# SN74ACT7801

## 1024 × 18 CLOCKED FIRST-IN, FIRST-OUT MEMORY

SCAS111 – D3489, APRIL 1990 – REVISED MAY 1991

### PARAMETER MEASUREMENT INFORMATION

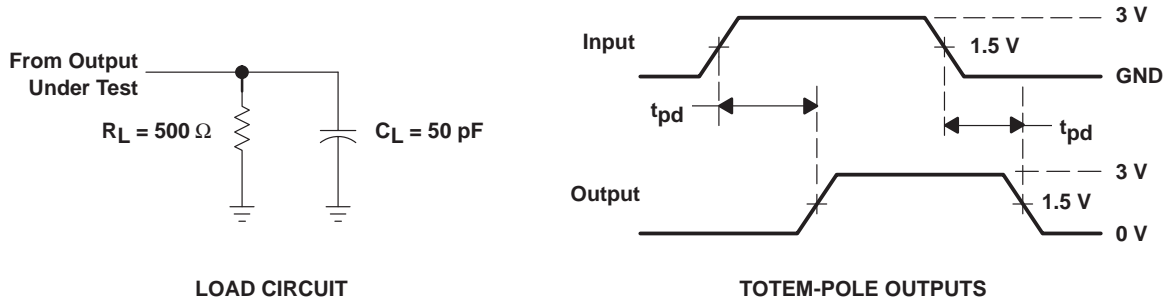
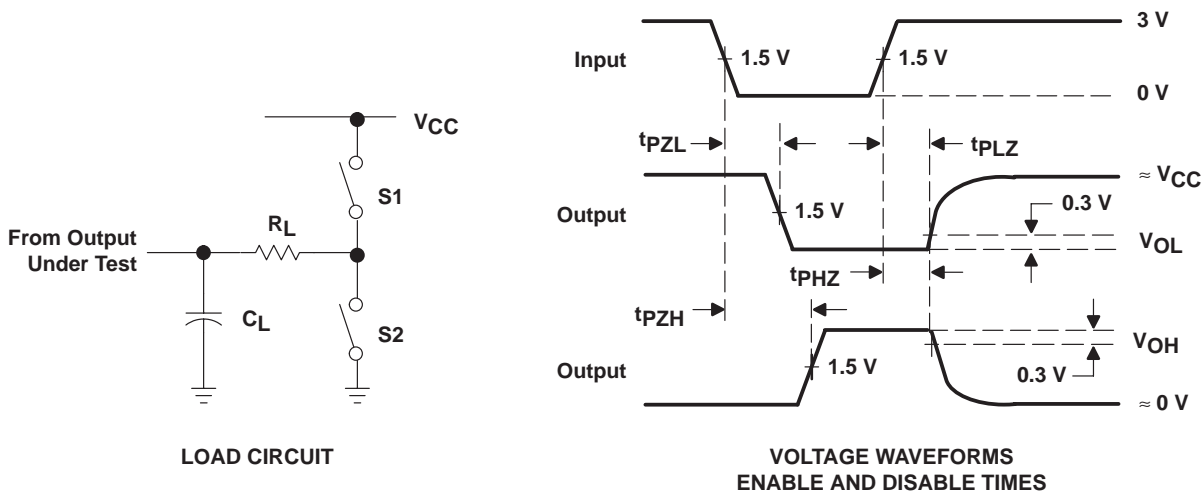


Figure 9. Standard CMOS Outputs (OR, Half Full, AF/AE)



PARAMETER	$R_L$	$C_L^\dagger$	S1	S2	
$t_{en}$	$t_{PZH}$	500 $\Omega$	50 pF	Open	Closed
	$t_{PZL}$			Closed	Open
$t_{dis}$	$t_{PHZ}$	500 $\Omega$	50 pF	Open	Closed
	$t_{PLZ}$			Closed	Open
$t_{pd}$ or $t_t$	–	50 pF	Open	Open	

<sup>†</sup> Includes probe and test-fixture capacitance.

Figure 10. 3-State Outputs (Any Q, OR)



**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74ACT7801-18FN	OBSOLETE	PLCC	FN	68		TBD	Call TI	Call TI
SN74ACT7801-18FNR	OBSOLETE	PLCC	FN	68		TBD	Call TI	Call TI
SN74ACT7801-18FNR	OBSOLETE	PLCC	FN	68		TBD	Call TI	Call TI
SN74ACT7801-20FN	OBSOLETE	PLCC	FN	68		TBD	Call TI	Call TI
SN74ACT7801-20FN	OBSOLETE	PLCC	FN	68		TBD	Call TI	Call TI

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

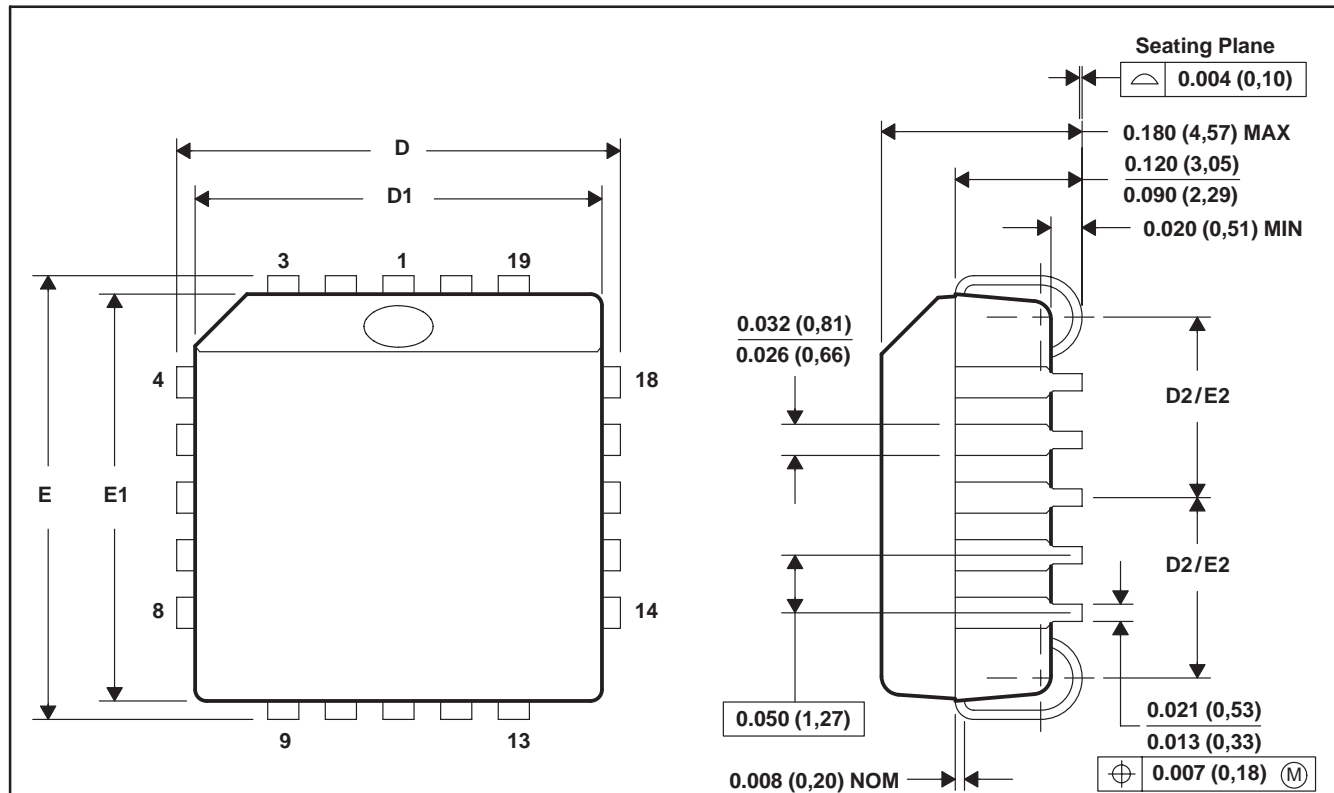
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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

FN (S-PQCC-J\*\*)

PLASTIC J-LEADED CHIP CARRIER

20 PIN SHOWN



NO. OF PINS **	D/E		D1/E1		D2/E2	
	MIN	MAX	MIN	MAX	MIN	MAX
20	0.385 (9,78)	0.395 (10,03)	0.350 (8,89)	0.356 (9,04)	0.141 (3,58)	0.169 (4,29)
28	0.485 (12,32)	0.495 (12,57)	0.450 (11,43)	0.456 (11,58)	0.191 (4,85)	0.219 (5,56)
44	0.685 (17,40)	0.695 (17,65)	0.650 (16,51)	0.656 (16,66)	0.291 (7,39)	0.319 (8,10)
52	0.785 (19,94)	0.795 (20,19)	0.750 (19,05)	0.756 (19,20)	0.341 (8,66)	0.369 (9,37)
68	0.985 (25,02)	0.995 (25,27)	0.950 (24,13)	0.958 (24,33)	0.441 (11,20)	0.469 (11,91)
84	1.185 (30,10)	1.195 (30,35)	1.150 (29,21)	1.158 (29,41)	0.541 (13,74)	0.569 (14,45)

4040005/B 03/95

- NOTES: A. All linear dimensions are in inches (millimeters).  
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